

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (U-MOS III)

## SSM6N15AFU

### Load Switching Applications

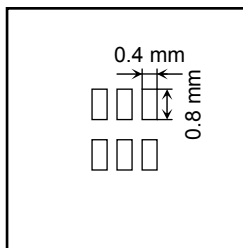
- 2.5 V drive
- N-ch 2-in-1
- Low ON-resistance:  $R_{DS(ON)} = 3.6 \Omega$  (max) (@ $V_{GS} = 4.0$  V)  
 $R_{DS(ON)} = 6.0 \Omega$  (max) (@ $V_{GS} = 2.5$  V)

### Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ ) (Q1, Q2 Common)

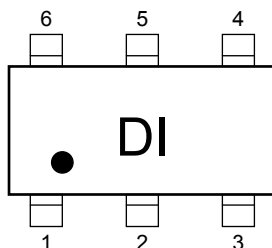
| Characteristics           | Symbol         | Rating     | Unit             |
|---------------------------|----------------|------------|------------------|
| Drain-Source voltage      | $V_{DSS}$      | 30         | V                |
| Gate-Source voltage       | $V_{GSS}$      | $\pm 20$   | V                |
| Drain current             | DC             | $I_D$      | mA               |
|                           | Pulse          | $I_{DP}$   |                  |
| Power dissipation         | $P_D$ (Note 1) | 300        | mW               |
| Channel temperature       | $T_{ch}$       | 150        | $^\circ\text{C}$ |
| Storage temperature range | $T_{stg}$      | -55 to 150 | $^\circ\text{C}$ |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

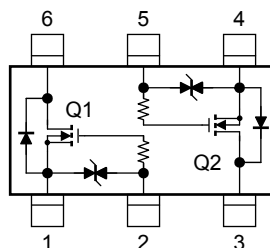
Note 1: Total rating  
 Mounted on FR4 board  
 (25.4 mm  $\times$  25.4 mm  $\times$  1.6 mm, Cu Pad: 0.32mm<sup>2</sup>  $\times$  6)



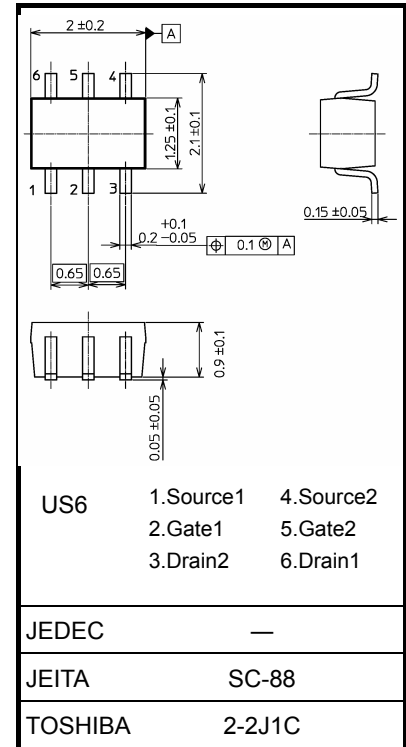
### Marking



### Equivalent Circuit (top view)



Unit: mm



Weight: 6.8 mg (typ.)

Start of commercial production  
 2010-11

## Electrical Characteristics (Ta = 25°C) (Q1, Q2 Common)

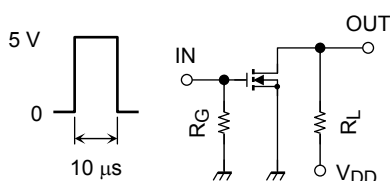
| Characteristics                | Symbol               | Test Condition                                            | Min | Typ.  | Max  | Unit |
|--------------------------------|----------------------|-----------------------------------------------------------|-----|-------|------|------|
| Drain-Source breakdown voltage | V (BR) DSS           | I <sub>D</sub> = 0.1 mA, V <sub>GS</sub> = 0 V            | 30  | —     | —    | V    |
|                                | V (BR) DSX           | I <sub>D</sub> = 0.1 mA, V <sub>GS</sub> = -10 V (Note 3) | 16  | —     | —    |      |
| Drain cut-off current          | I <sub>DSS</sub>     | V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V             | —   | —     | 1    | μA   |
| Gate leakage current           | I <sub>GSS</sub>     | V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V            | —   | —     | ±1   | μA   |
| Gate threshold voltage         | V <sub>th</sub>      | V <sub>DS</sub> = 3 V, I <sub>D</sub> = 0.1 mA            | 0.8 | —     | 1.5  | V    |
| Forward transfer admittance    | Y <sub>fs</sub>      | V <sub>DS</sub> = 3 V, I <sub>D</sub> = 10 mA (Note 2)    | 35  | —     | —    | mS   |
| Drain-Source ON resistance     | R <sub>DS (ON)</sub> | I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 4 V (Note 2)    | —   | 2.3   | 3.6  | Ω    |
|                                |                      | I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 2.5 V (Note 2)  | —   | 3.5   | 6.0  |      |
| Input capacitance              | C <sub>iss</sub>     | V <sub>DS</sub> = 3 V, V <sub>GS</sub> = 0 V, f = 1 MHz   | —   | 13.5  | —    | pF   |
| Output capacitance             | C <sub>oss</sub>     |                                                           | —   | 8.0   | —    |      |
| Reverse transfer capacitance   | C <sub>rss</sub>     |                                                           | —   | 6.5   | —    |      |
| Switching time                 | Turn-on time         | t <sub>on</sub>                                           | —   | 5.5   | —    | ns   |
|                                | Turn-off time        | t <sub>off</sub>                                          |     |       |      |      |
| Drain-source forward voltage   | V <sub>DSF</sub>     | I <sub>D</sub> = -100 mA, V <sub>GS</sub> = 0 V (Note 2)  | —   | -0.85 | -1.2 | V    |

Note 2: Pulse test

Note 3: If a reverse bias is applied between gate and source, this device enters V(BR)DSX mode. Note that the drain-source breakdown voltage is lowered in this mode.

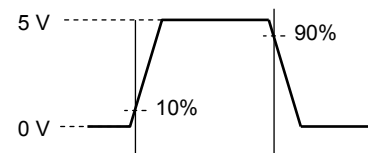
## Switching Time Test Circuit

### (a) Test circuit

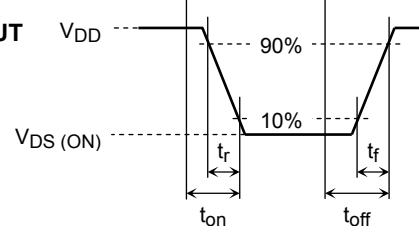


V<sub>DD</sub> = 5 V  
R<sub>G</sub> = 50 Ω  
Duty ≤ 1%  
V<sub>IN</sub>: t<sub>r</sub>, t<sub>f</sub> < 5 ns  
Common Source  
Ta = 25°C

### (b) V<sub>IN</sub>



### (c) V<sub>OUT</sub>



## Precaution

V<sub>th</sub> can be expressed as voltage between gate and source when low operating current value is I<sub>D</sub> = 0.1 mA for this product. For normal switching operation, V<sub>GS (on)</sub> requires higher voltage than V<sub>th</sub> and V<sub>GS (off)</sub> requires lower voltage than V<sub>th</sub>. (Relationship can be established as follows: V<sub>GS (off)</sub> < V<sub>th</sub> < V<sub>GS (on)</sub>)

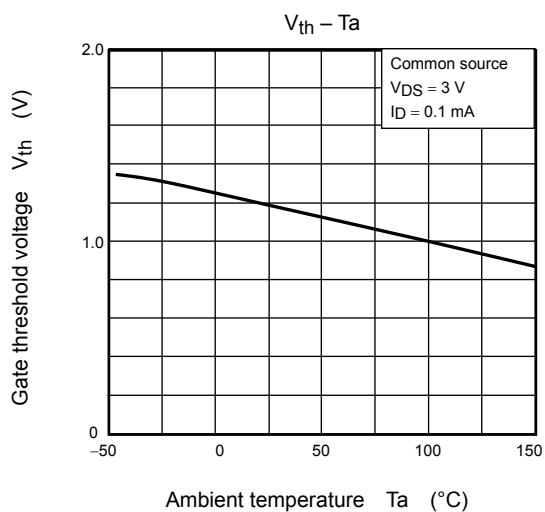
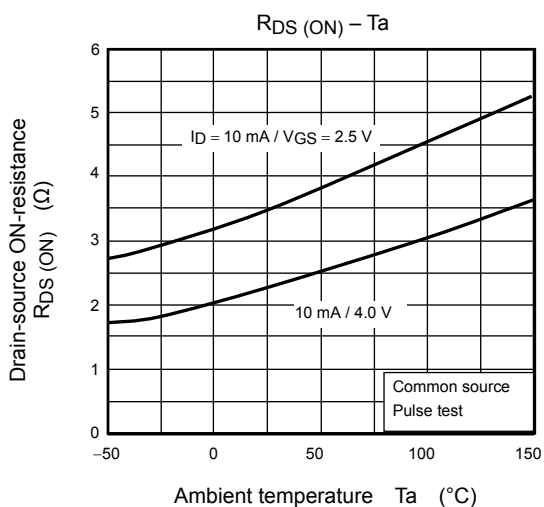
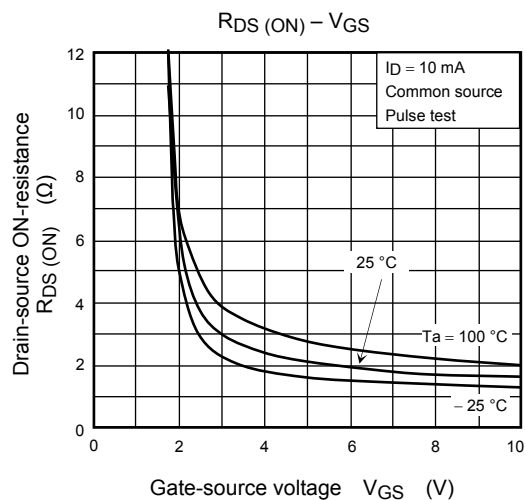
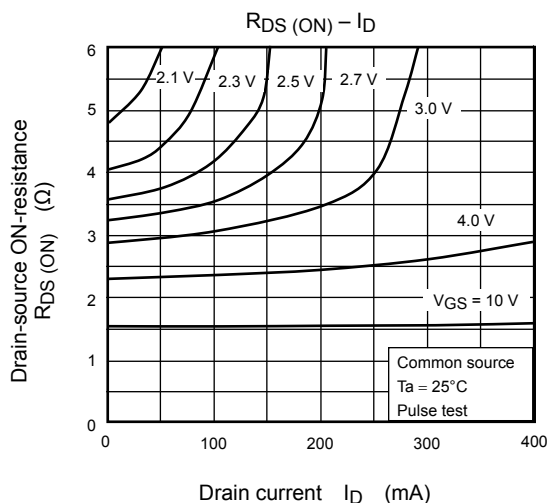
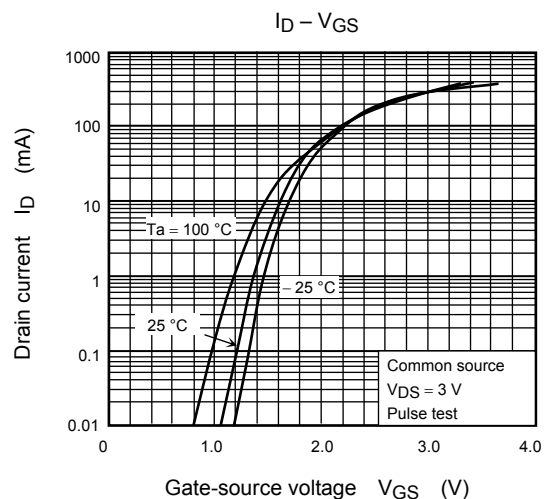
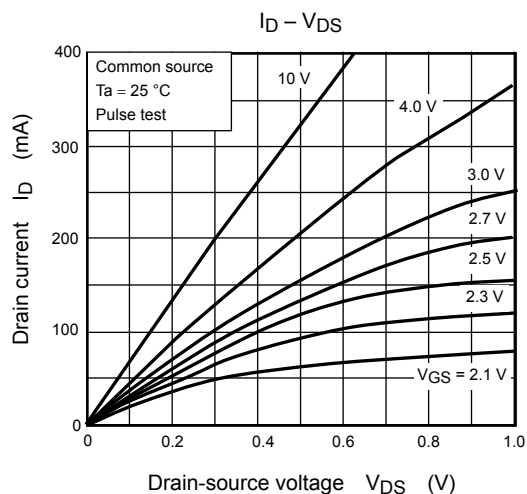
Please take this into consideration for using the device.

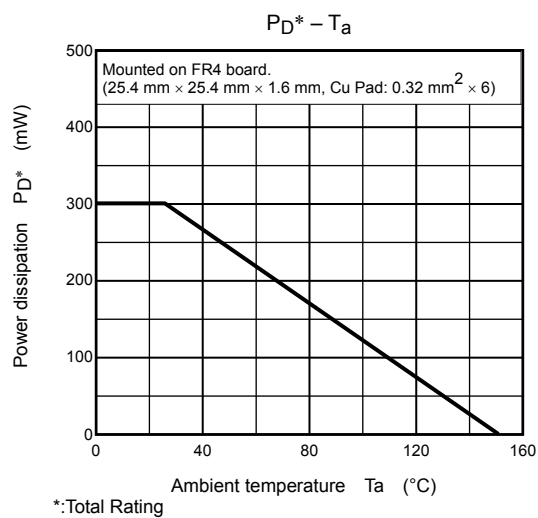
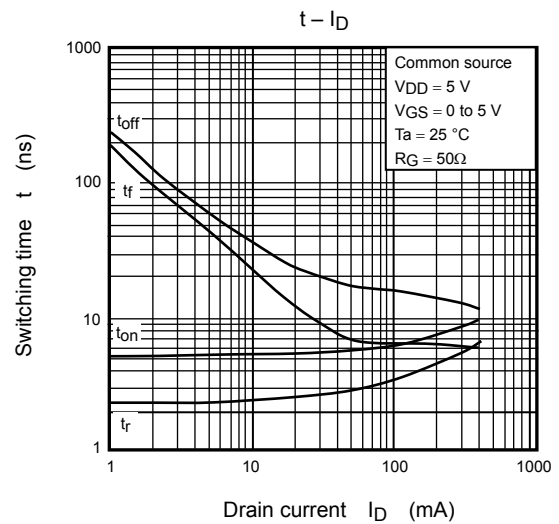
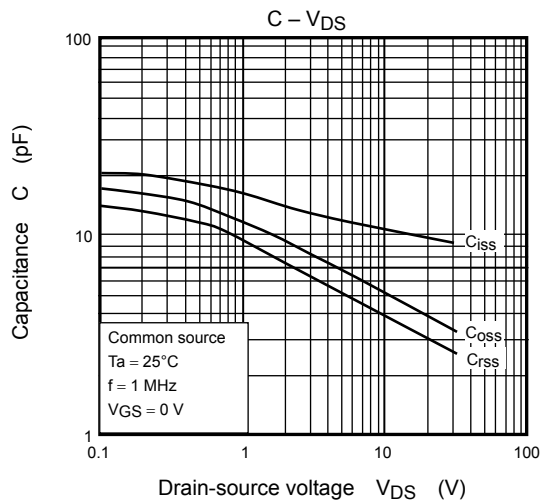
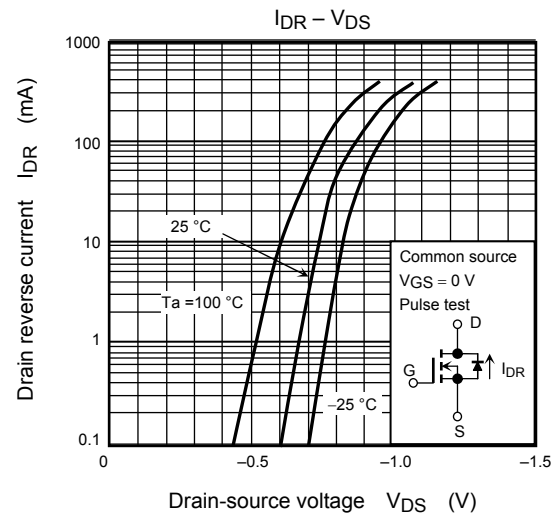
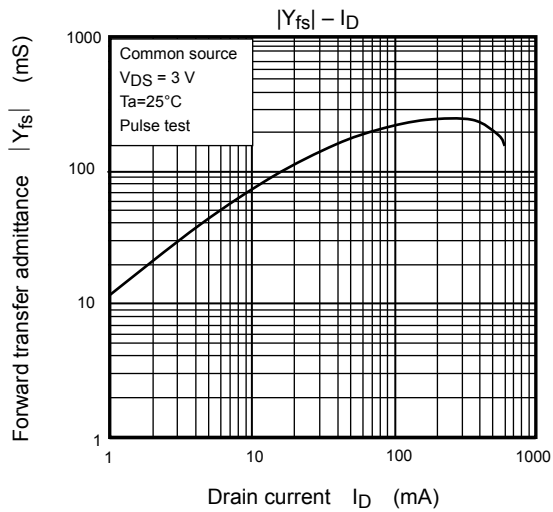
Do not use this device under avalanche mode. It may cause the device to break down.

## Handling Precaution

When handling individual devices (which are not yet mounting on a circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

Thermal resistance R<sub>th(ch-a)</sub> and power dissipation P<sub>D</sub> vary depending on board material, board area, board thickness and pad area. When using this device, please take heat dissipation into consideration





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